



MEG03-005660

November 18, 2008

TO: Commissioner for Patents
P.O. Box 1450
Alexandria, VA 22313-1450

CC: Examiner Monica Lewis
Art Unit#: 2822

FROM: Stephen B. Ackerman, Reg. No. 37,761
28 Davis Avenue
Poughkeepsie, N.Y. 12603

SUBJECT: Serial # 10/796,427
File Date March 9, 2004
Inventor: Mou-Shiung Lin, et al
Title: Wirebond Pad For Semiconductor Chip Or Wafer

CORRECTED DRAWINGS

Dear Sir:

In response to the Notice of Allowability dated October 16, 2008, changes have been made to the drawings and formal drawings are being filed (attached). One sheets of drawings are being submitted.

CERTIFICATE OF MAILING

I hereby certify that this correspondence is being deposited with the United States Postal Service as first class mail in an envelope addressed to: Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450 on *November 18, 2008*.

Signature 

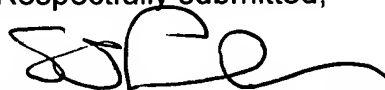
Stephen B. Ackerman, Reg. No. 37,761

Date: November 18, 2008

Figure 8 is missing line for number 34. These changes have been approved by the examiner in a phone conversation on March 13, 2008.

It is requested that should there be any problems with the drawings, the Examiner call the undersigned Attorney at (845) 452-5863.

Respectfully submitted,

A handwritten signature in black ink, appearing to read 'SBA', with a long, sweeping horizontal line extending to the right.

Stephen B. Ackerman, Reg. No, 37,761

Enclosures